Radiation Effects on FinFET ZRAMs

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Outline

- •ZRAM operation
- Experimental conditions
- •TID effects and scaling trends
 - Back-gate pulse programming
 - GIDL programming
- Conclusions



Background

- > Zero capacitor DRAM, a real 1T DRAM cell.
- Floating body effects provide the basis for ZRAM operation.
- > High speed, low power, and potentially high scalability.



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ZRAM Operation



- Method 1: Back-gate pulse stores charge in body; then front gate pulse releases charge from body.
- Method 2: Front-gate pulse combined with drain pulse stores charge in the body by GIDL (gate induced drain leakage), then drain pulse sweeps the charge out of body by forward biasing the body/drain junction.

Programming of ZRAM cell

Time (s)



Experimental Details

Devices

- n-MOS and p-MOS FinFETs on UNIBOND[®] SOI.
- Fin width ranges from 50 to 2410 nm.
- Channel length ranges from 80 nm to 20 μm.
- The front-gate dielectric is 2 nm SiO_2 .

ZRAM Tests

- I_D/I_S current vs. time with V_G/V_{BG} and V_D pulses.
- Programmed via back gate pulse or GIDL.

Irradiation Test Conditions:

ON-state: $V_G = 0.5 \text{ V}$, $V_D = V_S = V_{sub} = 0 \text{ V}$ (NMOS); OFF-state: $V_G = V_S = V_{sub} = 0 \text{ V}$, $V_D = -0.5 \text{ V}$ (PMOS); Total dose: 0 ~ 1000 krad(SiO₂) with 10-keV X-ray

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Transient Effects on ZRAM Cell Back-Gate Pulse Programming



Fin width dependence of ΔI_D back-gate pulse

ZRAM/pMOS has larger memory window than nMOS with same fin width, for these devices and programming conditions.

- For other technologies, relative nMOS/pMOS responses may be different.
- Memory window of ZRAM cell decreases with decreasing fin width.
 - Side gate E-field limits charge storage for narrow fin devices.
 - > Negative scaling trend.

Total Dose Effects on ZRAM Programmed by Back-Gate Pulse



GIDL Programming of FinFETs



> Memory window is larger for GIDL than for back-gate pulse.

> Charge storage occurs primarily near the drain.

Gate Length Dependence



Memory Window vs. Fin Width



decreasing fin width.

Retention vs. Pulse Width

Retention defined here as time to 50% loss of excess current



Radiation Effects on ZRAMs Programmed by GIDL



Comparison of GIDL and Back-Gate Programming: TID Effects



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For this technology,
ZRAM programmed by
GIDL is more tolerant to
total-dose irradiation than
ZRAM programmed by
back-gate pulse.



Conclusions

- ✓ ZRAMs programmed by GIDL are more tolerant to total-dose irradiation than ZRAMs programmed by back-gate pulse.
- Charge trapping in BOX during the write pulse can enhance ZRAM memory window size and retention.
- Memory window scaling and total dose response are very promising for ZRAMs programmed by GIDL.



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